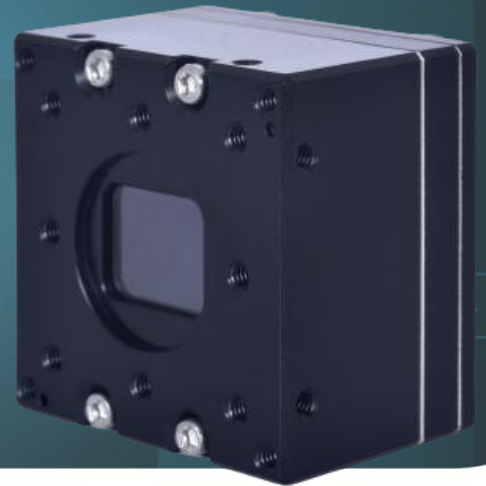


HIGH-RESOLUTION UNCOOLED
THERMAL IMAGING CORE

Xenics
EXOSENS GROUP

Crius XP 640 (NEW)



*EXTREME PERFORMANCE WITH ULTRA-
COMPACT VGA THERMAL IMAGING CORE*

KEY FEATURES



**ADVANCED SHUTTERLESS IMAGING
WITH EMBEDDED CORRECTION**



**CONTOUR ENHANCEMENT: SHARPER
DRI AND SUPERIOR OBJECT CLARITY**



**COLUMN AND TEMPORAL DENOISING:
NETD halved from 40 mK to 20 mK**



**CONTRAST SHARPNESS CORE FOR
AUTOFOCUS MANAGEMENT**

The Crius XP (Extreme Performance) 640 is a cutting-edge uncooled LWIR thermal core, delivering ultra-sharp 640×480 resolution with a 12 μm pixel pitch and NETD <20 mK for exceptional thermal sensitivity.

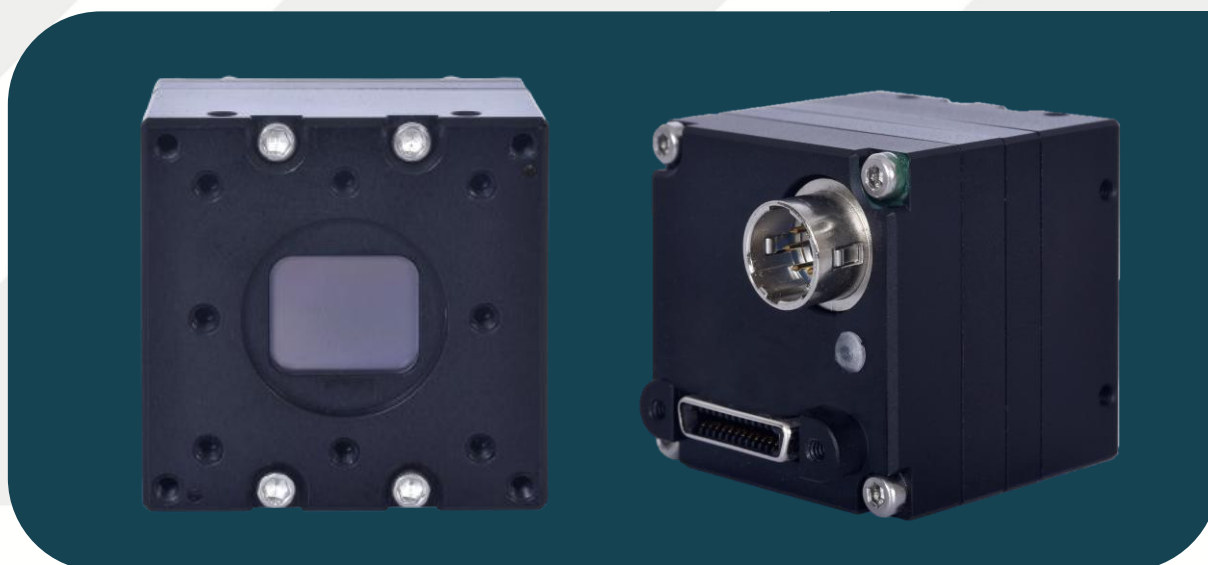
Engineered for mission-critical defense applications, it features a next-gen shutterless algorithm for rapid imaging (<0.7s) and enhanced stability across extreme temperatures. Advanced contour enhancement deliver sharper contrast, superior dynamic range, and significantly improved DRI and object recognition.

Its compact SWaP design and flexible interface options ensure seamless integration into high-demand platforms, making it the ideal choice for modern thermal imaging systems.



exosens.com

Crius XP 640 (NEW)



KEY PERFORMANCES

Sensor	Micro-bolometer technology
Resolution / Pixel Pitch	640 x 480 pixels / 12 μ m
Spectral Range	8 – 14 μ m
Max NETD (F/1 ; 300K ; 30 Hz)	< 20 mK with denoising
Operating temperature range	-40°C to +70°C
Power consumption (DF40)	< 1.2 W
Qualification	MIL-STD-810G – Method 514 Vibration: 10Hz - 2kHz 13.95g per axis 10h per axis

FUNCTIONS & INTERFACES

Image processing	BPC (Bad Pixel Correction), NUC (Non-Uniformity Correction), Shutterless NUC
Image optimisation	AGC (Automatic Gain Control)
Output options	CL, SDI, DF40
Additional option	On DF40: Handheld/manual control interface + micro display interface
Dimensions (L x B x H) (DF40)	30 x 30 x 23 mm ³
Weight (DF40)	< 38 gr

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REVEAL THE INVISIBLE